

**IN THE CLAIMS:**

Please cancel claims 1-18 without prejudice or disclaimer. ✓

Please amend the claims as follows: ✓

22  
CS  
B-1  
19. (Amended) A multi-layer substrate structure comprising:  
at least one layer having generic electrical features altered to customize said layer,  
wherein said electrical features include vias,  
wherein said vias are selectively filled with one of a conducting material and an  
insulating material.

CS  
B-1  
22. (Amended) The multi-layer substrate structure in claim 19, further comprising a  
second layer similar to said layer and having said generic electrical features altered differently than  
said layer to customize said second layer differently than said layer.

CS  
23. (Amended) The multi-layer substrate structure in claim 19, wherein said layer is for  
being changes into a plurality of differently customized layers.

24. (Amended) The multi-layer substrate structure in claim 19, wherein said layer  
includes a generic grid of vias useful with a plurality of differently customized layers.

25. (Amended) The multi-layer substrate structure in claim 19, wherein said layer  
includes a generic pattern of wiring useful with a plurality of differently customized layers.